

RACON 12 S, SMT, 4.7 ± 0.8 N, 1 NO

LBL NRFND



fields of application

- > Measurement-control-regulation
- > Mechanical and system engineering
- > Automotive
- > Electro-medical

special features

- Gold contacts, reliable switching with low currents
- > Special tactile feedback
- > Different operating forces
- > Variable overall heights due to plunger
- > Terminal technology: SMT or THT
- > Traceability through product identification
- > sealable (tested media see Downloads)

CE

description

Our top-quality RACON 12 tactile switches – in the dimensions 12 x 12 mm – feature an unmistakeable click, high switching reliability, a sealed contact system and castability. That has made RACON the standard in many industries. Whether for automotive applications, systems with keycaps, or membrane keyboards, RACON impresses in the THT or SMT versions – for your application too.

RACON 12 tactile switches can be arranged individually, in rows or as key blocks. When used beneath membrane overlays, the RACON key switches should be combined with plungers. Suitable for the most important soldering techniques.

Soldering bath for THT versions

Reflow soldering for SMT versions

Vapor phase soldering for SMT versions

Manual soldering

Processing of the SMT designs with SMT automatic assembly machines

IMDS entry

technical data

>	general
•	90

Color blue
Operating temperature, min. -40 °C

Operating temperature, max. 90 °C
Storage temperature, min. -50 °C
Storage temperature, max. 90 °C
illuminated No
Soldering Reflow

Solder heat resistance according

to standard

direct links

> RAFI eCatalog

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DIN EN 60068-2-58

RAFI GmbH & Co. KG



Packaging Blister
Packaging unit 750 pcs.
net weight 1.5 g

Operating life 1,000,000 cycles B10 1,300,000 cycles

Degree of protection, front side, according to DIN EN 60529 IPx7
Degree of protection, rear side, according to DIN EN 60529 IPx7
MSL Moisture Sensitivity Level 1
Corrosive gas testing according to Yes

standard

MOQ order 750 pcs.

RoHS compliant Yes

REACH compliant Yes

Component material Elastomer

Product code 4C

> mounting diameters

Outside dimension, length 12 mm
Outside dimension, width 12 mm

Installation height $4.95 \pm 0.1 \text{ mm}$ Grid, min. $12.50 \times 15.24 \text{ mm}$

> mechanical data

Actuation function momentary contact function

Operating force, max. 8 N

Operating force, min. $4.7 \pm 0.8 \text{ N}$ Switching travel $0.66 \pm 0.1 \text{ mm}$

Contact function 1 NO

Contact system Snap-action contact

SPST - Single Pole Single Throw

Contact material Gold
Solderability Yes
Terminal on the rear SMT

> electrical data

Rated voltage, min.

Rated voltage, max.

Rated current, min.

Rated current, max.

O.1 A

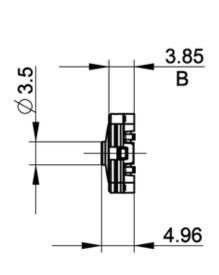
Rated power, max.

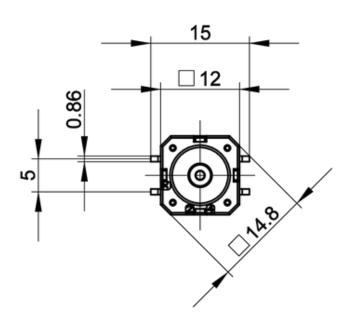
1 W



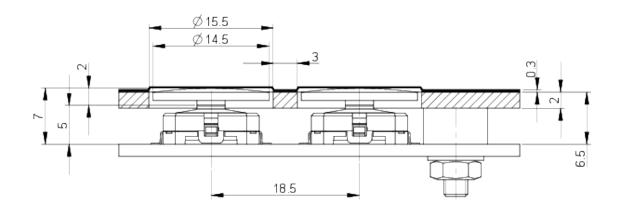
drawings

Dimensioned drawing



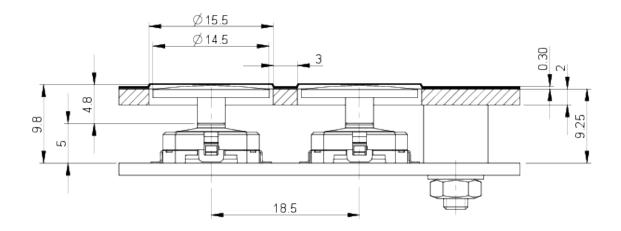


System drawing



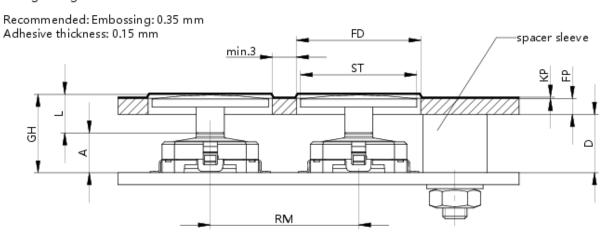


System drawing



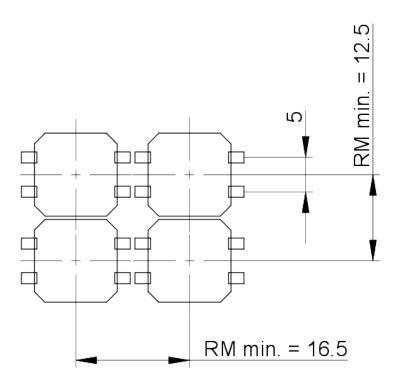
System drawing

SMT gullwing connection

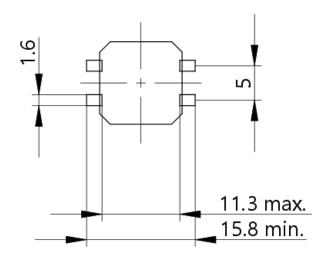




PCB drawing



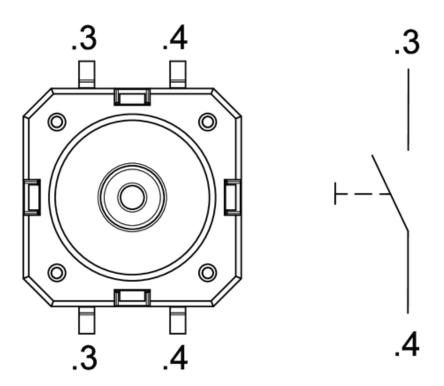
PCB drawing



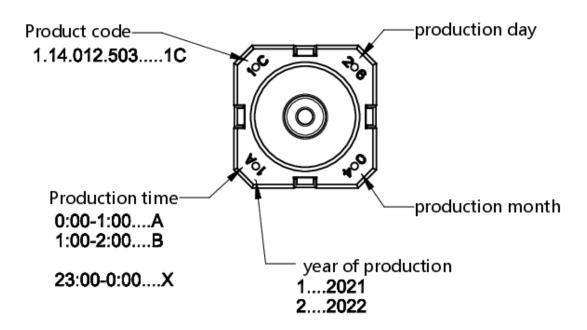
PCB-Pad component side



Schematic diagram

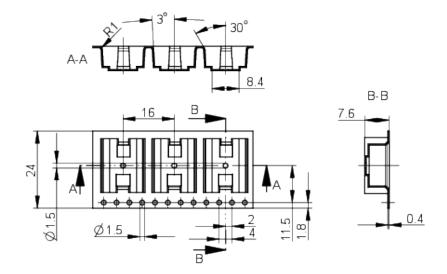


Product labeling drawing





Packaging drawing



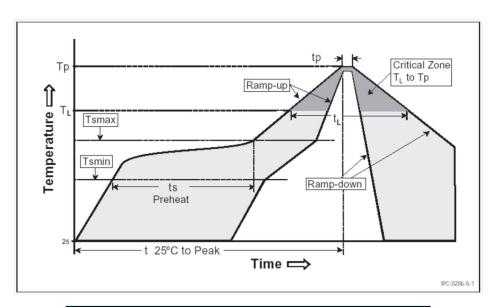


mounting

RAFI soldering profile for ROHS compliant reflow components



Publication date: October 7, 2021



Parameter	RAFI values
Gradient (T _L to T _P)	max. 3°C / s
Preheating zone Minimum temperature (T _{smin}) Maximum temperature (T _{smax}) Time (from min. to max.) (ts)	150°C 200°C 60 - 120 s
Gradient (T _{smax} to T _L)	max. 3°C/s
$\label{eq:total_continuity} \begin{tabular}{ll} Time over \\ melting temperature (T_L) \\ time (t_L) \\ \end{tabular}$	217°C 60 – 150 s
Peak temperature (T _P)	max. 260°C (+0°C)
Time within peak temperature – 5°C (tp)	20-40 s
Gradient ramp down	max. 6°C / s
Time difference from 25°C to peak temperature	max. 8 minutes

The reflow soldering profile is based on the definition of Jedec J-STD-020D.

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